

TR-42.3 Subcommittee

Telecommunications Administration, Pathways, Spaces, Bonding and Grounding

Date: Monday, June 6, 2022

Time: 11:15 am - 1:15 pm Central Time (CT)

Location: Virtual, GoToWebinar

Chair: Cindy Montstream – Legrand, 860-208-5261
Vice Chair: Jonathan Jew – J&M Consultants, 415-515-4304

Meeting GoToWebinar Registration Link: Monday, June 6, 2022, 11:15am - 1:15pm CT

Meeting Schedule URL:

TR-42 June 2022 Meeting Schedule

TIA Important Notice of Participation

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TIA is actively seeking participation in TR-42 standards projects from the user and general interest categories

- 1. Administrative/General Business
- 1.1. Call to Order
- 1.2. Attendance (Call Quorum, Introductions, Roster)
- 1.3. Current Meeting Agenda Review and Approval (TR423-2022-06-008)
- 1.4. Previous Meeting Report Review and Approval (TR423-2022-01-006)



1.5. TIA Intellectual Property Rights (Early Disclosure Policy)

TIA's Intellectual Property Rights Policy can be found in Statements of Policy (ANNEX C) and other clauses and annexes of TIA Standards Development Procedures. Participants in the work of the TIA Formulating Groups are urged to review the appropriate sections. Individual participants are encouraged to notify TIA of any patent(s) or published pending patent application(s) of which they are aware that may be essential to the practice of a proposed TIA Publication, including requirements introduced through normative references, early in the development to reduce the possibility for delays in the development process and increase the likelihood that the proposed TIA Publication will become a Standard. However, a Patent Holder who has provided TIA with a TIA Patent Holder Statement with respect to the applicable proposed TIA Publication need not (but may elect to) identify its specific patent(s) or published pending patent application(s) that may be essential to the practice of the proposed TIA Publication in question. Patent searches are not required to comply with the TIA Intellectual Property Rights Policy.

1.6. Distribution of documents and contributions

Document #	Title	Company	Contributor
2022-01-006	Report January 2022 Virtual Meeting TR-42.3 Jew		Jew
2022-06-007	ASHRAE Class B & C in Thermal Guidelines 5 th Edition TR-42.3 Jew		Jew
2022-06-008	22-06-008 Notice & Agenda June 2022 Virtual Meeting TR-42.3 Montstream		Montstream
2022-06-009	D6-009 TIA-569-E-1 D1 Comments with Editor's Recommendations TR-42.3 Emplit		Emplit
2022-06-010	22-06-010 PAR Reaffirmation of ANSI/TIA-5048 TR-42.3 Montstream		Montstream
2022-06-011	Copper-Clad Steel Grounding Conductors in 2023 NEC	Leviton	Poulsen

1.7. List of Standards and TSBs from Subcommittee

Document	Title	Date of Revision	Current Status
ANSI/TIA-569-E	Telecommunications Pathways & Spaces	2019	Published
ANSI/TIA-569-E-1	Telecommunications Pathways and Spaces Addendum 1 – Revised Temperature and Humidity Requirements	2022	Committee Ballot
ANSI/TIA-606-D	Administration Standard For Telecommunications Infrastructure	2021	Published
ANSI/TIA-607-D Generic Telecommunications Bonding & Grounding (Earthing) For Customer Premises 20		2019	Published
ANSI/TIA-607-D Addendum 1	Generic Telecommunications Bonding & Grounding (Earthing) For Customer Premises- Addendum 1	2021	Published



ANSI/TIA-5048	Automated Infrastructure Management (Aim) Systems- Requirements, Data Exchange and Applications	2017	Published
ANSI/TIA-5048-1	Automated Infrastructure Management (Aim) Systems- Requirements, Data Exchange and Applications – Addendum 1		Published

1.8. Chair's Report and General Items

2. Old Business

2.1. ANSI/TIA-569-E-1 Committee Ballot

- ASHRAE Class B & C in Thermal Guidelines 5th Edition contribution (TR423-2022-06-007)
- Resolve TIA-569-E-1 Draft 1 Comments (TR423-2022-06-009)
- Next Steps (Committee or Industry Ballot)

3. New Business

3.1. ANSI/TIA-5048

Reaffirmation PAR (TR423-2022-06-010)

3.2. Impact of NEC Modification on ANSI/TIA-607

- NEC allowing copper-clad steel grounding conductors are being permitted for communications applications (800.100A2 and 810.21A) under "other corrosion-resistant conductive material" in 2023 NEC
- Copper-Clad Grounding Conductors Contribution (TR423-2022-06-011)
 - Update on allowing copper-clad steel grounding conductors in NEC

3.3. Other New Business

- 4. Action Items
- 5. Upcoming Meetings

5.1. Next Meeting

October 3-7 – Location TBD (Hybrid)

6. Adjournment



AVAILABILITY OF MEETING DOCUMENTS:

TR-42 members/participants are instructed to download contributions and other meeting documents from TIA Connect (connect.tiaonline.org) before the meeting.

To access the meeting's contributions, please follow the directions below:

- Go to connect.tiaonline.org
- Enter your *Username* (your email address in the TIA database)
- Enter your Password
- Click "LOGIN"
- Click the "Communities" tab and then select "All My Communities"
- Scroll down the page and select "TR-42.3 Commercial Building Telecommunications Pathways and Spaces"
- Click on "Documents" and then select meeting folder

NEW CONTRIBUTIONS:

Contributions shall use the approved templates and specific wording provided by TIA. Contributions affecting a document are to include a TIA cover sheet, proposed text to be included in the document, and the rationale/substantiation for the contribution. File templates are available on TIA Connect under the Standards Procedure Toolbox tab in the Forms folder.

Early submittal and posting of contributions for consideration in meetings is highly encouraged. Contributions shall be submitted to the EDC as soon as possible and then posted to the appropriate meeting folder on TIA Connect by the EDC as soon after receipt as possible, preferably within one business day. All contributions shall be posted to the appropriate location on TIA Connect no later than 12:00 noon EST on the Monday preceding the week of the meeting in which the contribution is to be considered (example: if the meeting will be held on Thursday the 20th, the contributions shall be posted by noon on Monday the 10th).

LATE CONTRIBUTIONS:

Contributions provided to the EDC within 24-hours of the meeting shall be classified as "late contributions." They may be considered in the meeting to which they are addressed at the discretion of the chair. All late contributions shall be provided to the EDC and to the committee members on a memory stick or other electronic media. All late contributions shall be posted to TIA Connect within one week of meeting adjournment.

Questions and comments on this agenda should be submitted to:

Cindy Montstream, Chair	cindy.montstream@legrand.us	(860) 208-5261
Jonathan Jew, Vice-Chair	jew@j-and-m.com	(415) 515-4304